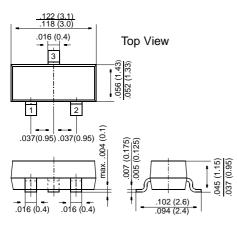
BC817, BC818

Small Signal Transistors (NPN)

<u>SOT-23</u>



Dimensions in inches and (millimeters)

Pin configuration 1 = Base, 2 = Emitter, 3 = Collector.

FEATURES

 NPN Silicon Epitaxial Planar Transistors for switching, AF driver and amplifier applications.



- Especially suited for automatic insertion in thick- and thin-film circuits.
- These transistors are subdivided into three groups -16, -25 and -40 according to their current gain.
- As complementary types, the PNP transistors BC807 and BC808 are recommended.

MECHANICAL DATA

Case: SOT-23 Plastic Package Weight: approx. 0.008 g Marking code

Туре	Marking
BC817-16	6A
-25	6B
-40	6C
BC818-16	6E
-25	6F
-40	6G

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified

		Symbol	Value	Unit
Collector-Emitter Voltage	BC817 BC818	V _{CES} V _{CES}	50 30	V V
Collector-Emitter Voltage	BC817 BC818	V _{CEO} V _{CEO}	45 25	V V
Emitter-Base Voltage		V _{EBO}	5	V
Collector Current		I _C	800	mA
Peak Collector Current		I _{CM}	1000	mA
Peak Base Current		I _{BM}	200	mA
Peak Emitter Current		-I _{EM}	1000	mA
Power Dissipation at $T_{SB} = 50 \text{ °C}$		P _{tot}	310 ¹⁾	mW
Junction Temperature		Tj	150	°C
Storage Temperature Range		T _S	-65 to +150	°C

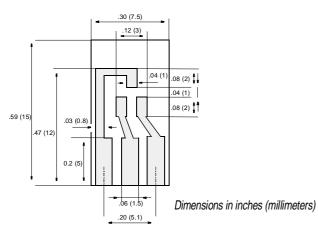


BC817 THRU BC818

ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified

	Symbol	Min.	Тур.	Max.	Unit		
DC Current Gain at V_{CE} = 1 V, I_C = 100 mA Current Gain Group-16 -25 -40 at V_{CE} = 1 V, I_C = 300 mA -16 -25 -40	hFE hFE hFE hFE hFE hFE	100 160 250 60 100 170	- - - - -	250 400 600 -	- - - - -		
Thermal Resistance Junction Substrate Backside	R _{thSB}	-	-	3201)	K/W		
Thermal Resistance Junction to Ambient Air	R _{thJA}	-	-	450 ¹⁾	K/W		
Collector Saturation Voltage at I_{C} = 500 mA, I_{B} = 50 mA	V _{CEsat}	_	-	0.7	V		
Base-Emitter Voltage at V_{CE} = 1 V, I_C = 300 mA	V _{BE}	-	-	1.2	V		
Collector-Emitter Cutoff Currentat $V_{CE} = 45 \text{ V}$ BC817at $V_{CE} = 25 \text{ V}$ BC818at $V_{CE} = 25 \text{ V}$, $T_j = 150 \text{ °C}$	I _{CES} I _{CES} I _{CES}	_ _ _		100 100 5	nA nA μA		
Emitter-Base Cutoff Current at V _{EB} = 4 V	I _{EBO}	_	-	100	nA		
Gain-Bandwidth Product at V _{CE} = 5 V, I _C = 10 mA, f = 50 MHz	f _T	-	100	-	MHz		
Collector-Base Capacitance at V_{CB} = 10 V, f = 1 MHz	C _{CBO}	_	12		pF		
¹⁾ Device on fiberglass substrate, see layout							

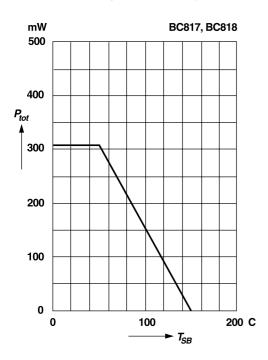


Layout for R_{thJA} test Thickness: Fiberglass 0.059 in (1.5 mm) Copper leads 0.012 in (0.3 mm)

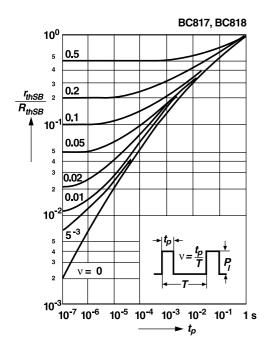


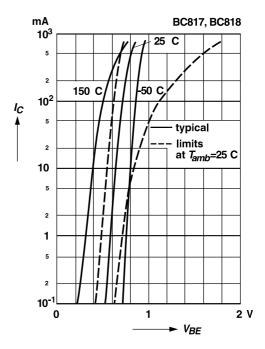
RATINGS AND CHARACTERISTIC CURVES BC817, BC818

Admissible power dissipation versus temperature of substrate backside Device on fiberglass substrate, see layout

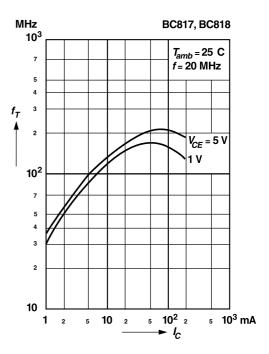


Pulse thermal resistance versus pulse duration (normalized) Device on fiberglass substrate, see layout





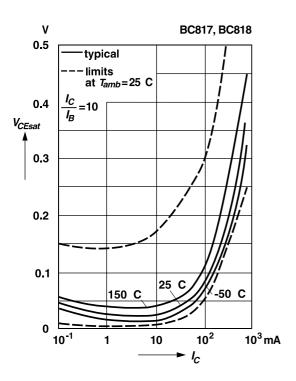
Gain-bandwidth product versus collector current



GENERAL SEMICONDUCTOR®

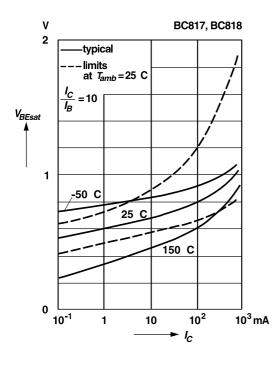
Collector current versus base-emitter voltage

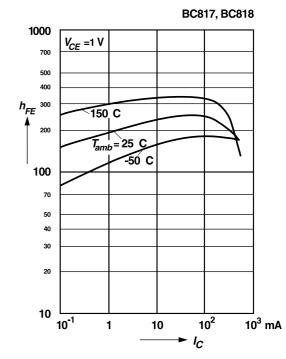
RATINGS AND CHARACTERISTIC CURVES BC817, BC818



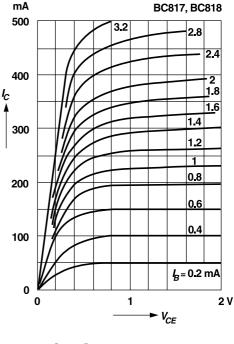
Collector saturation voltage versus collector current

Base saturation voltage versus collector current





Common emitter collector characteristics

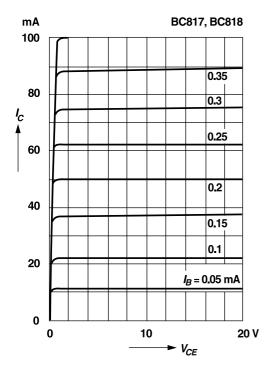


DC current gain versus collector current

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RATINGS AND CHARACTERISTIC CURVES BC817, BC818

Common emitter collector characteristics



mΑ BC817, BC818 500 /0.9 0.85 400 I_c 300 0.8 200 0.75 100 $V_{BE} = 0.7 \text{ V}$ 0 1 0 2 V → V_{CE}

Common emitter collector characteristics

